

RF Power Field Effect Transistors

N-Channel Enhancement-Mode Lateral MOSFETs

RF power transistors designed for CW and pulse applications operating at 1300 MHz. These devices are suitable for use in defense and commercial CW and pulse applications, such as DME/IFF systems.

- Typical Pulse Performance: $V_{DD} = 50$ Vdc, $I_{DQ} = 100$ mA

Signal Type	P_{out} (W)	f (MHz)	G_{ps} (dB)	η_D (%)	IRL (dB)
Pulse (200 μ sec, 10% Duty Cycle)	250 Peak	1300	22.7	57.0	-18

- Typical CW Performance: $V_{DD} = 50$ Vdc, $I_{DQ} = 10$ mA, $T_C = 61^\circ\text{C}$

Signal Type	P_{out} (W)	f (MHz)	G_{ps} (dB)	η_D (%)	IRL (dB)
CW	230 CW	1300	20.0	53.0	-25

- Capable of Handling a Load Mismatch of 10:1 VSWR, @ 50 Vdc, 1300 MHz at all Phase Angles, 250 W Pulse Peak Power, 10% Duty Cycle, 200 μ sec

Features

- Characterized with series equivalent large-signal impedance parameters
- Internally matched for ease of use
- Qualified up to a maximum of 50 V_{DD} operation
- Characterized from 20 to 50 V for extended power range
- Integrated ESD protection
- Greater negative gate-source voltage range for improved Class C operation
- In tape and reel. R5 suffix = 50 units, 56 mm tape width, 13-inch reel.

MMRF1005HR5
MMRF1005HSR5

1300 MHz, 250 W, 50 V
LATERAL N-CHANNEL
RF POWER MOSFETs

NI-780H-2L
MMRF1005HR5

NI-780S-2L
MMRF1005HSR5

Table 1. Maximum Ratings

Rating	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	-0.5, +120	Vdc
Gate-Source Voltage	V_{GS}	-6.0, +10	Vdc
Storage Temperature Range	T_{stg}	-65 to +150	$^\circ\text{C}$
Case Operating Temperature	T_C	150	$^\circ\text{C}$
Operating Junction Temperature (1)	T_J	225	$^\circ\text{C}$
Total Device Dissipation @ $T_C = 25^\circ\text{C}$ Derate above 25°C	P_D	476 2.38	W W/ $^\circ\text{C}$

Table 2. Thermal Characteristics

Characteristic	Symbol	Value (2)	Unit
Thermal Resistance, Junction to Case Pulse: Case Temperature 65°C , 250 W Peak, 200 μ sec Pulse Width, 10% Duty Cycle, 50 Vdc, $I_{DQ} = 100$ mA, 1300 MHz CW: Case Temperature 77°C , 235 W CW, 50 Vdc, $I_{DQ} = 10$ mA, 1300 MHz	$Z_{\theta JC}$ $R_{\theta JC}$	0.07 0.42	$^\circ\text{C}/\text{W}$

1. Continuous use at maximum temperature will affect MTTF.

2. Refer to [AN1955](#), *Thermal Measurement Methodology of RF Power Amplifiers*. Go to <http://www.freescale.com/rf> and search for AN1955.

Table 3. ESD Protection Characteristics

Test Methodology	Class
Human Body Model (per JESD22-A114)	2
Machine Model (per EIA/JESD22-A115)	B
Charge Device Model (per JESD22-C101)	IV

Table 4. Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
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Off Characteristics

Gate-Source Leakage Current ($V_{GS} = 5\text{ Vdc}$, $V_{DS} = 0\text{ Vdc}$)	I_{GSS}	—	—	1	μAdc
Drain-Source Breakdown Voltage ($V_{GS} = 0\text{ Vdc}$, $I_D = 50\text{ mA}$)	$V_{(BR)DSS}$	120	—	—	Vdc
Zero Gate Voltage Drain Leakage Current ($V_{DS} = 50\text{ Vdc}$, $V_{GS} = 0\text{ Vdc}$)	I_{DSS}	—	—	10	μAdc
Zero Gate Voltage Drain Leakage Current ($V_{DS} = 90\text{ Vdc}$, $V_{GS} = 0\text{ Vdc}$)	I_{DSS}	—	—	20	μAdc

On Characteristics

Gate Threshold Voltage ($V_{DS} = 10\text{ Vdc}$, $I_D = 640\text{ }\mu\text{Adc}$)	$V_{GS(th)}$	1.0	1.8	2.7	Vdc
Gate Quiescent Voltage ($V_{DD} = 50\text{ Vdc}$, $I_D = 100\text{ mAdc}$, Measured in Functional Test)	$V_{GS(Q)}$	2.0	2.4	3.0	Vdc
Drain-Source On-Voltage ($V_{GS} = 10\text{ Vdc}$, $I_D = 1.58\text{ Adc}$)	$V_{DS(on)}$	0.1	0.25	0.3	Vdc

Dynamic Characteristics ⁽¹⁾

Reverse Transfer Capacitance ($V_{DS} = 50\text{ Vdc} \pm 30\text{ mV(rms)ac}$ @ 1 MHz, $V_{GS} = 0\text{ Vdc}$)	C_{rss}	—	1.2	—	pF
Output Capacitance ($V_{DS} = 50\text{ Vdc} \pm 30\text{ mV(rms)ac}$ @ 1 MHz, $V_{GS} = 0\text{ Vdc}$)	C_{oss}	—	58	—	pF
Input Capacitance ($V_{DS} = 50\text{ Vdc}$, $V_{GS} = 0\text{ Vdc} \pm 30\text{ mV(rms)ac}$ @ 1 MHz)	C_{iss}	—	340	—	pF

Functional Tests (In Freescale Test Fixture, 50 ohm system) $V_{DD} = 50\text{ Vdc}$, $I_{DQ} = 100\text{ mA}$, $P_{out} = 250\text{ W Peak}$ (25 W Avg.), $f = 1300\text{ MHz}$
Pulse, 200 μsec Pulse Width, 10% Duty Cycle

Power Gain	G_{ps}	21.5	22.7	24.0	dB
Drain Efficiency	η_D	53.5	57.0	—	%
Input Return Loss	IRL	—	-18	-9	dB

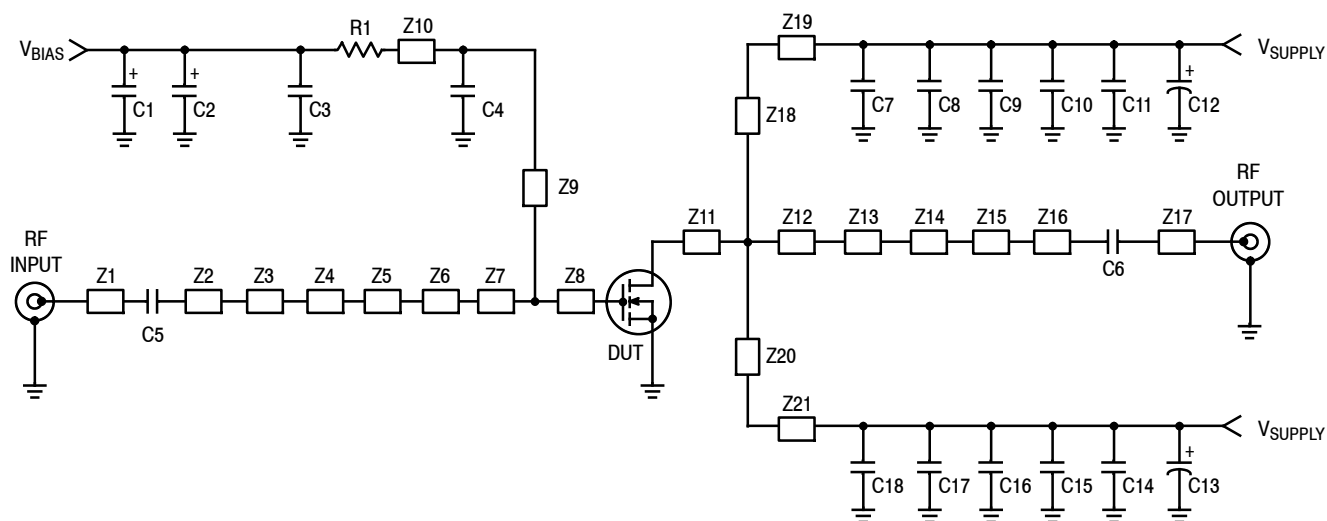
Typical CW Performance (In Freescale CW Application Circuit, 50 ohm system) $V_{DD} = 50\text{ Vdc}$, $I_{DQ} = 10\text{ mA}$, $P_{out} = 230\text{ W CW}$, $f = 1300\text{ MHz}$,
 $T_C = 61^\circ\text{C}$

Power Gain	G_{ps}	—	20.0	—	dB
Drain Efficiency	η_D	—	53.0	—	%
Input Return Loss	IRL	—	-25	—	dB

Load Mismatch (In Freescale Application Test Fixture, 50 ohm system) $V_{DD} = 50\text{ Vdc}$, $I_{DQ} = 100\text{ mA}$, $P_{out} = 250\text{ W Peak}$ (25 W Avg.),
 $f = 1300\text{ MHz}$, Pulse, 200 μsec Pulse Width, 10% Duty Cycle

VSWR 10:1 at all Phase Angles	Ψ	No Degradation in Output Power
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1. Part internally input matched.



Z1	0.447" x 0.063" Microstrip	Z11	0.162" x 1.160" Microstrip
Z2	0.030" x 0.084" Microstrip	Z12	0.419" x 1.160" Microstrip
Z3	0.120" x 0.063" Microstrip	Z13	0.468" x 0.994" Microstrip
Z4	0.855" x 0.293" Microstrip	Z14	0.131" x 0.472" Microstrip
Z5	0.369" x 0.825" Microstrip	Z15	0.264" x 0.222" Microstrip
Z6	0.203" x 0.516" Microstrip	Z16	0.500" x 0.111" Microstrip
Z7	0.105" x 0.530" Microstrip	Z17	0.291" x 0.063" Microstrip
Z8	0.105" x 0.530" Microstrip	Z18, Z20	0.105" x 0.388" Microstrip
Z9*	0.116" x 0.050" Microstrip	Z19*, Z21*	0.854" x 0.052" Microstrip
Z10	0.122" x 0.050" Microstrip		

*Line length includes microstrip bends.

Figure 1. MMRF1005HR5(HSR5) Test Circuit Schematic — 1300 MHz, Pulse

Table 5. MMRF1005HR5(HSR5) Test Circuit Component Designations and Values — 1300 MHz, Pulse

Part	Description	Part Number	Manufacturer
C1, C2	22 μ F, 35 V Tantalum Capacitors	T491X226K035AT	Kemet
C3, C11, C14	0.1 μ F, 50 V Chip Capacitors	CDR33BX104AKWS	AVX
C4, C6, C7, C18	100 pF Chip Capacitors	ATC800B101JT500XT	ATC
C5	4.7 pF Chip Capacitor	ATC100B4R7CT500XT	ATC
C8, C17	1000 pF Chip Capacitors	ATC100B102JT50XT	ATC
C9, C16	1000 pF Chip Capacitors	ATC700B102FT50XT	ATC
C10, C15	10K pF Chip Capacitors	ATC200B103KT50XT	ATC
C12, C13	470 μ F, 63 V Electrolytic Capacitors	MCGPR63V477M13X26-RH	Multicomp
R1	15 Ω , 1/4 W Chip Resistor	CRCW120615R0FKEA	Vishay
PCB	Rogers RO4350B, 0.030", $\epsilon_r = 3.66$	—	MTL

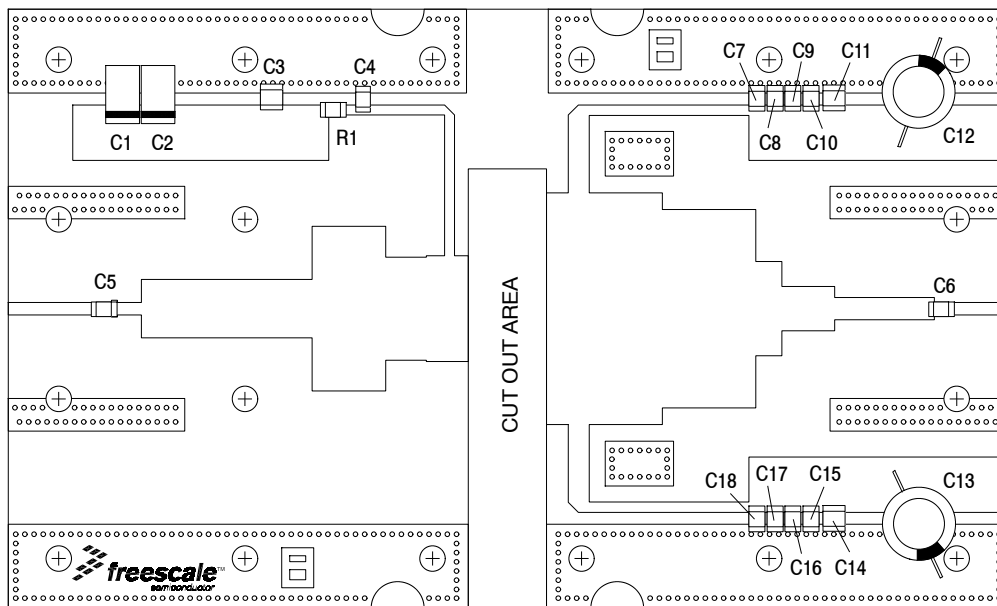


Figure 2. MMRF1005HR5(HSR5) Test Circuit Component Layout — 1300 MHz, Pulse

TYPICAL CHARACTERISTICS — PULSE

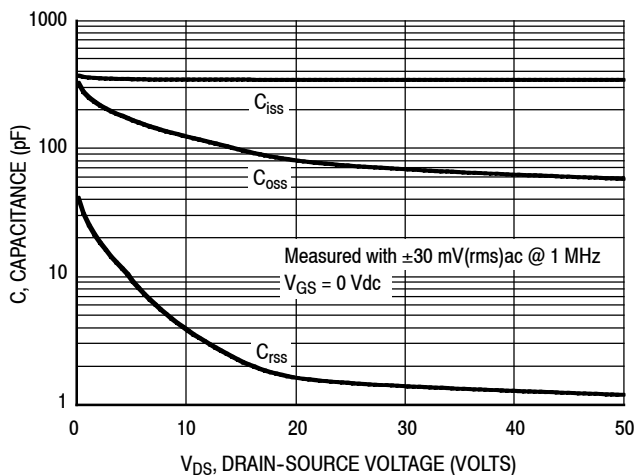


Figure 3. Capacitance versus Drain-Source Voltage

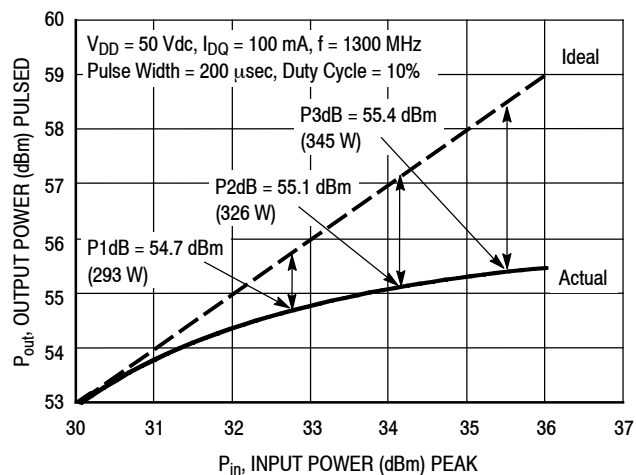


Figure 4. Output Power versus Input Power

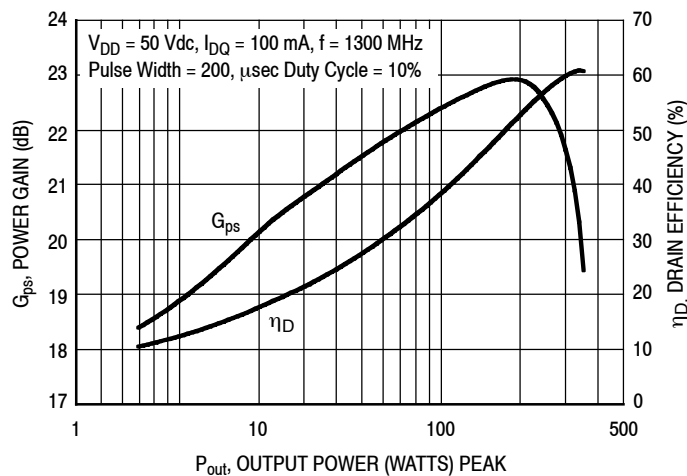


Figure 5. Power Gain and Drain Efficiency versus Output Power

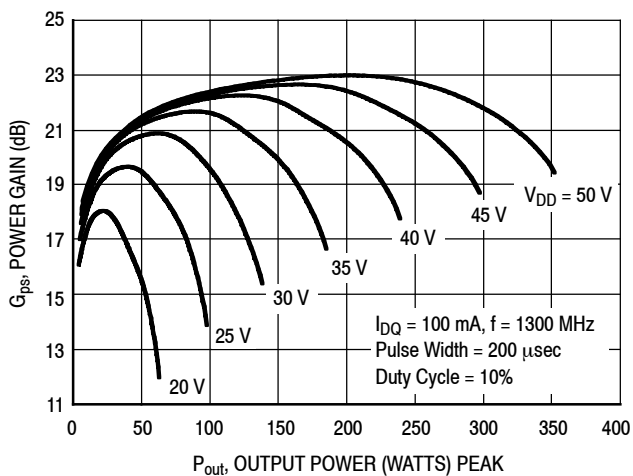


Figure 6. Power Gain versus Output Power

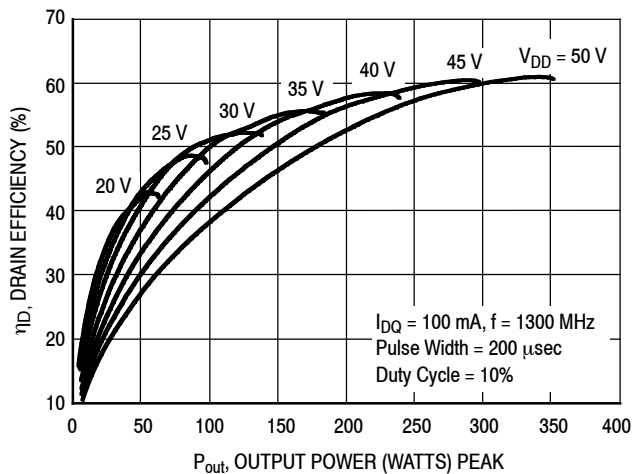


Figure 7. Efficiency versus Output Power

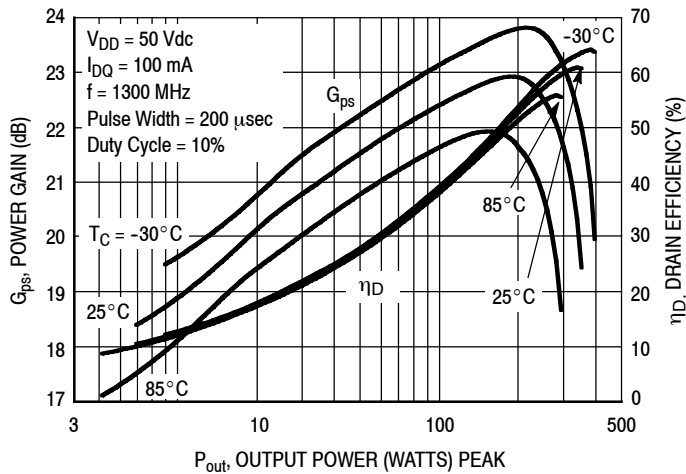
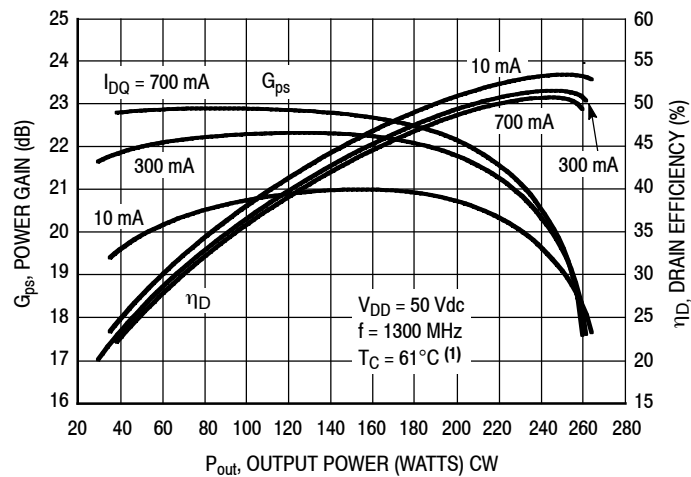


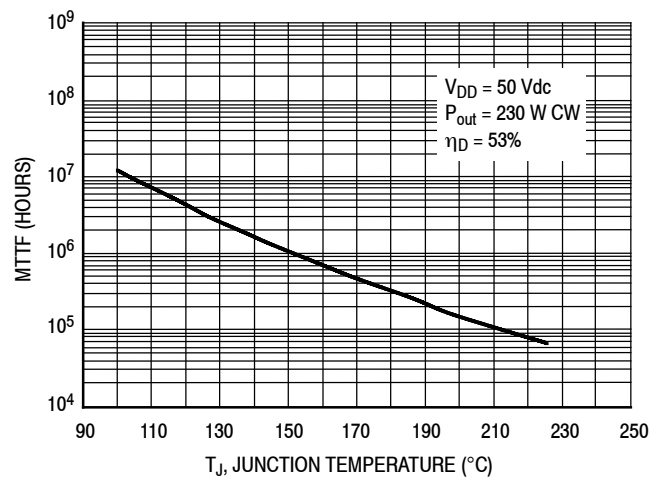
Figure 8. Power Gain and Drain Efficiency versus Output Power

TYPICAL CHARACTERISTICS — CW



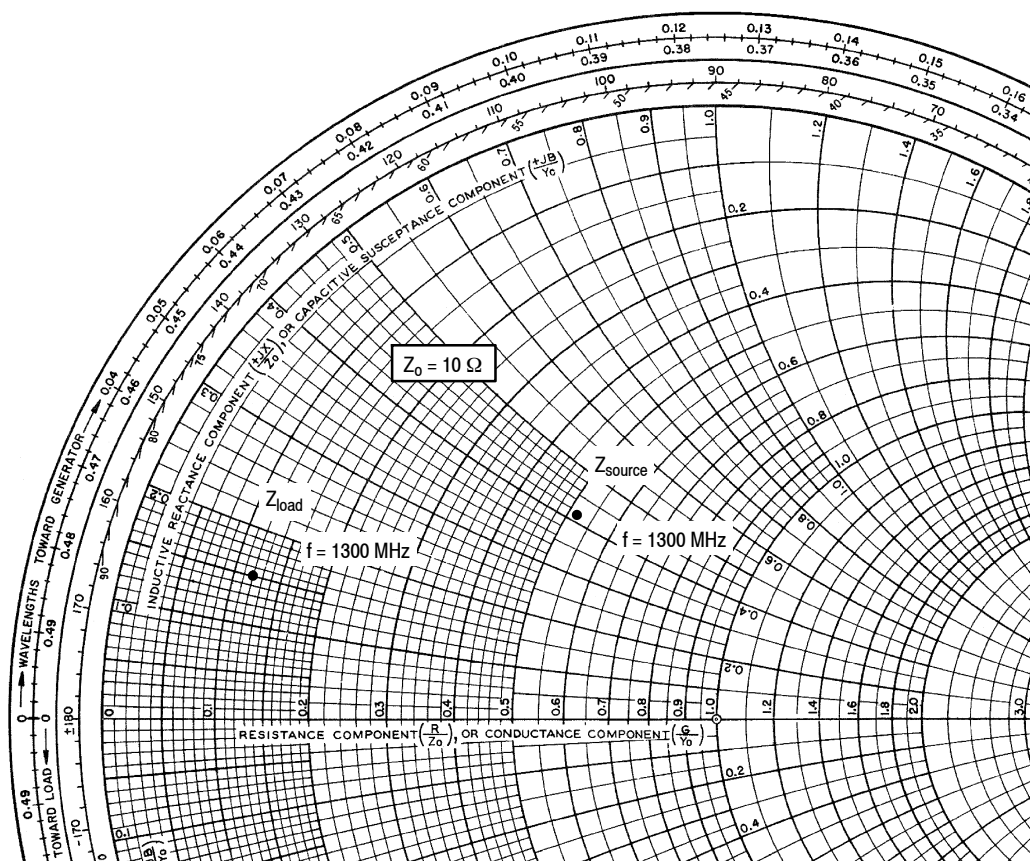
1. Data for graph was collected in a water-cooled test fixture. The water inlet temperature = 25°C.

Figure 9. CW Power Gain and Drain Efficiency versus Output Power



MTTF calculator available at <http://www.freescale.com/rf/calculators>.

Figure 10. MTTF versus Junction Temperature — CW



$V_{DD} = 50 \text{ Vdc}$, $I_{DQ} = 100 \text{ mA}$, $P_{out} = 250 \text{ W Peak}$

f MHz	Z_{source} Ω	Z_{load} Ω
1300	$5.32 + j4.11$	$1.17 + j1.48$

Z_{source} = Test circuit impedance as measured from gate to ground.

Z_{load} = Test circuit impedance as measured from drain to ground.

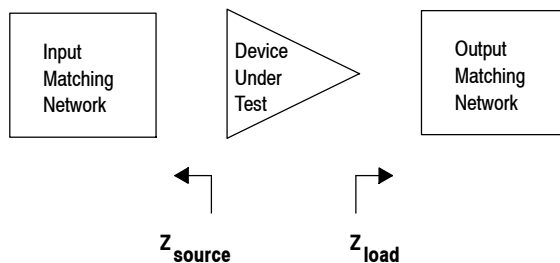
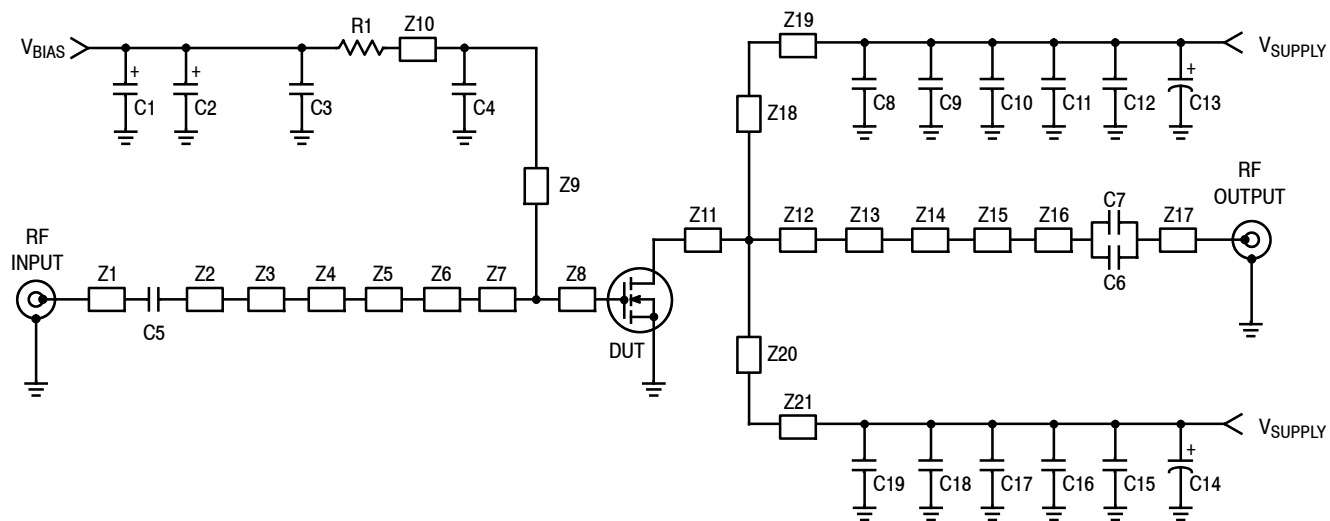


Figure 11. Series Equivalent Source and Load Impedance — Pulse



Z1	0.447" x 0.063" Microstrip	Z11	0.162" x 1.160" Microstrip
Z2	0.030" x 0.084" Microstrip	Z12	0.419" x 1.160" Microstrip
Z3	0.120" x 0.063" Microstrip	Z13	0.468" x 0.994" Microstrip
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*Line length includes microstrip bends.

Figure 12. MMRF1005HR5(HSR5) Application Circuit Schematic — 1300 MHz, CW

Table 6. MMRF1005HR5(HSR5) Application Circuit Component Designations and Values — 1300 MHz, CW

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C4, C6, C7, C8, C19	100 pF Chip Capacitors	ATC800B101JT500XT	ATC
C5	4.7 pF Chip Capacitor	ATC100B4R7CT500XT	ATC
C9, C18	1000 pF Chip Capacitors	ATC100B102JT50XT	ATC
C10, C17	1000 pF Chip Capacitors	ATC700B102FT50XT	ATC
C11, C16	10K pF Chip Capacitors	ATC200B103KT50XT	ATC
C13, C14	470 μ F, 63 V Electrolytic Capacitors	MCGPR63V477M13X26-RH	Multicomp
R1	15 Ω , 1/4 W Chip Resistor	CRCW120615R0FKEA	Vishay
PCB	Rogers RO4350B, 0.030", $\epsilon_r = 3.66$	—	MTL

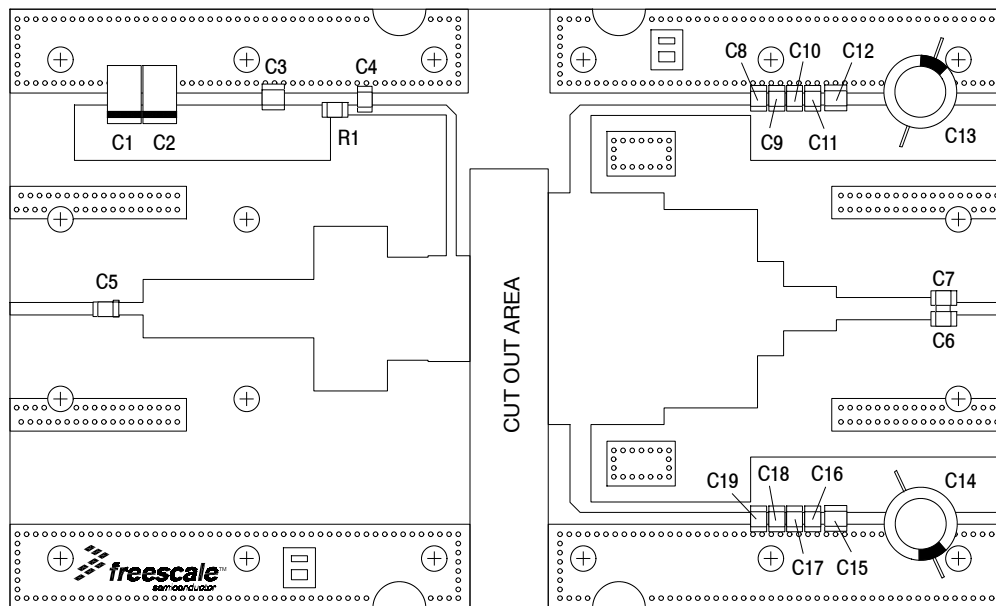
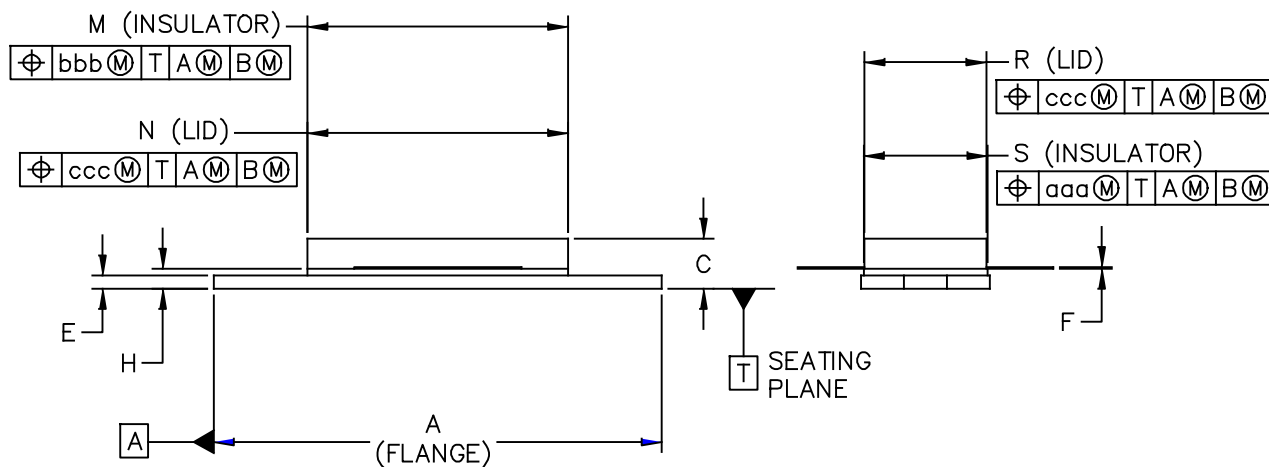
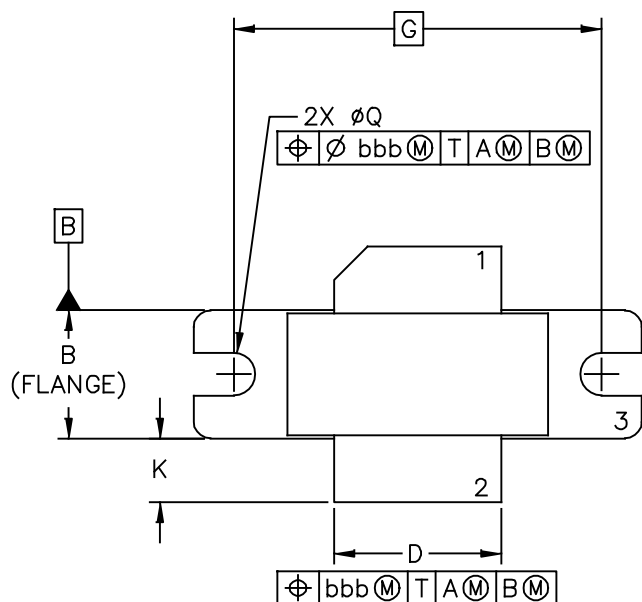


Figure 13. MMRF1005HR5(HSR5) Application Circuit Component Layout — 1300 MHz, CW

PACKAGE DIMENSIONS



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TITLE: NI-780		DOCUMENT NO: 98ASB15607C		REV: G	
		CASE NUMBER: 465-06		31 MAR 2005	
		STANDARD: NON-JEDEC			

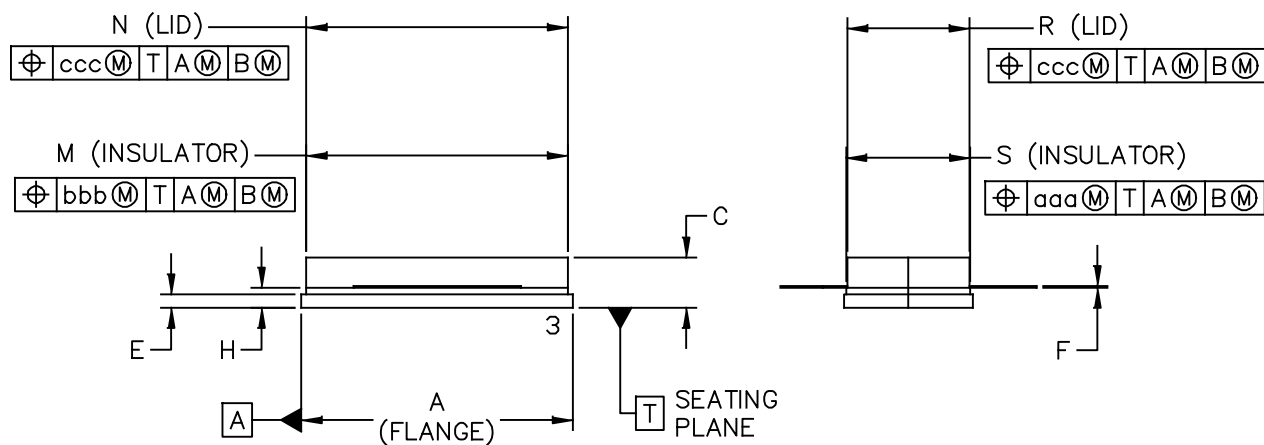
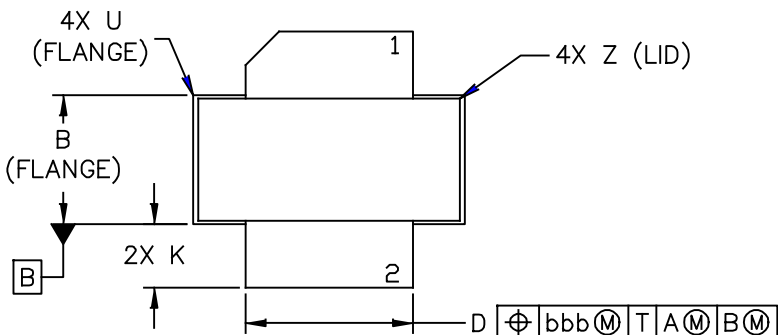
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M–1994.
2. CONTROLLING DIMENSION: INCH.
3. DELETED
4. DIMENSION H IS MEASURED .030 (.762) AWAY FROM PACKAGE BODY.

STYLE 1:

- PIN 1. DRAIN
2. GATE
3. SOURCE

DIM	INCH MIN MAX	MILLIMETER MIN MAX	DIM	INCH MIN MAX	MILLIMETER MIN MAX
A	1.335 – 1.345	33.91 – 34.16	R	.365 – .375	9.27 – 9.53
B	.380 – .390	9.65 – 9.91	S	.365 – .375	9.27 – 9.52
C	.125 – .170	3.18 – 4.32	aaa	– .005 –	– 0.127 –
D	.495 – .505	12.57 – 12.83	bbb	– .010 –	– 0.254 –
E	.035 – .045	0.89 – 1.14	ccc	– .015 –	– 0.381 –
F	.003 – .006	0.08 – 0.15	–	– – –	– – –
G	1.100 BSC	27.94 BSC	–	– – –	– – –
H	.057 – .067	1.45 – 1.7	–	– – –	– – –
K	.170 – .210	4.32 – 5.33	–	– – –	– – –
M	.774 – .786	19.66 – 19.96	–	– – –	– – –
N	.772 – .788	19.6 – 20	–	– – –	– – –
Q	ø.118 – ø.138	ø3 – ø3.51	–	– – –	– – –
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TITLE: NI–780			DOCUMENT NO: 98ASB15607C		REV: G
			CASE NUMBER: 465–06		31 MAR 2005
			STANDARD: NON–JEDEC		



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TITLE: NI-780S			DOCUMENT NO: 98ASB16718C		REV: H
			CASE NUMBER: 465A-06		31 MAR 2005
			STANDARD: NON-JEDEC		

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1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M—1994.
2. CONTROLLING DIMENSION: INCH.
3. DELETED
4. DIMENSION H IS MEASURED .030 (0.762) AWAY FROM PACKAGE BODY.

STYLE 1:

- PIN 1. DRAIN
2. GATE
3. SOURCE

INCH			MILLIMETER			INCH				MILLIMETER		
DIM	MIN	MAX	MIN	MAX	DIM	MIN	MAX	MIN	MAX	MIN	MAX	
A	.805	— .815	20.45	— 20.7	U	—	— .040	—	— 1.02			
B	.380	— .390	9.65	— 9.91	Z	—	— .030	—	— 0.76			
C	.125	— .170	3.18	— 4.32	aaa	—	.005 —	—	0.127 —			
D	.495	— .505	12.57	— 12.83	bbb	—	.010 —	—	0.254 —			
E	.035	— .045	0.89	— 1.14	ccc	—	.015 —	—	0.381 —			
F	.003	— .006	0.08	— 0.15	—	—	— —	—	— —			
H	.057	— .067	1.45	— 1.7	—	—	— —	—	— —			
K	.170	— .210	4.32	— 5.33	—	—	— —	—	— —			
M	.774	— .786	19.61	— 20.02	—	—	— —	—	— —			
N	.772	— .788	19.61	— 20.02	—	—	— —	—	— —			
R	.365	— .375	9.27	— 9.53	—	—	— —	—	— —			
S	.365	— .375	9.27	— 9.52	—	—	— —	—	— —			
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TITLE: NI—780S					DOCUMENT NO: 98ASB16718C				REV: H			
					CASE NUMBER: 465A—06				31 MAR 2005			
					STANDARD: NON—JEDEC							

PRODUCT DOCUMENTATION

Refer to the following resources to aid your design process.

Application Notes

- AN1955: Thermal Measurement Methodology of RF Power Amplifiers

Engineering Bulletins

- EB212: Using Data Sheet Impedances for RF LDMOS Devices

REVISION HISTORY

The following table summarizes revisions to this document.

Revision	Date	Description
0	Dec. 2013	• Initial Release of Data Sheet
1	Apr. 2015	• Tables 5 and 6, Test Circuit Component Designations and Values: updated PCB description to reflect most current board specifications from Rogers, pp. 3, 8 • Added CW application circuit for 1300 MHz as follows: schematic, component designations and values, and component layout, pp. 8–9

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